

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low $R_{DS(ON)}$ and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

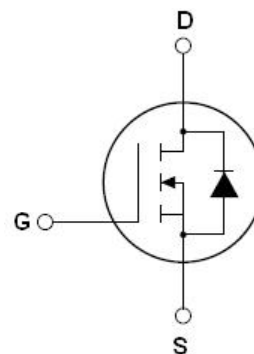
Features

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger (OBC)

| | | |
|------------------------|-----|----|
| $V_{DS\ min@T_{jmax}}$ | 710 | V |
| $R_{DS(ON)TYP}$ | 85 | mΩ |
| I_D | 36 | A |
| Q_g | 55 | nC |



Schematic diagram

✧ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

| Device | Device Package | Marking |
|------------|----------------|------------|
| NCE65NF099 | TO-220 | NCE65NF099 |



Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

| Parameter | Symbol | Value | Unit |
|--|------------------|----------|---------------------|
| Drain-Source Voltage ($V_{GS}=0V$) | V_{DS} | 650 | V |
| Gate-Source Voltage ($V_{DS}=0V$) AC ($f>1\text{ Hz}$) | V_{GS} | ± 30 | V |
| Gate-Source Voltage ($V_{DS}=0V$) DC | V_{GS} | ± 20 | V |
| Continuous Drain Current at $T_c=25^\circ\text{C}$ | $I_D (DC)$ | 36 | A |
| Continuous Drain Current at $T_c=100^\circ\text{C}$ | $I_D (DC)$ | 25.2 | A |
| Pulsed drain current (Note 1) | $I_{DM (pluse)}$ | 108 | A |
| Maximum Power Dissipation ($T_c=25^\circ\text{C}$) | P_D | 346 | W |
| Derate above 25°C | | 2.30 | W/ $^\circ\text{C}$ |
| Single pulse avalanche energy (Note 2) | E_{AS} | 324 | mJ |
| Avalanche current (Note 1) | I_{AS} | 9 | A |
| Repetitive Avalanche energy, t_{AR} limited by T_{jmax} (Note 1) | E_{AR} | 3.9 | mJ |

| Parameter | Symbol | Value | Unit |
|---|----------------|------------|------|
| Drain Source voltage slope, $V_{DS} \leq 480V$, | dv/dt | 50 | V/ns |
| Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$ | dv/dt | 50 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55...+175 | °C |

* limited by maximum junction temperature

Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---|------------|-------|-------|
| Thermal Resistance, Junction-to-Case (Maximum) | R_{thJC} | 0.43 | °C /W |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R_{thJA} | 62 | °C /W |

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|---------------------|---|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =1mA | 650 | | | V |
| Zero Gate Voltage Drain Current(Tc=25℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | | 10 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =650V,V _{GS} =0V | | | 400 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =500uA | 3 | 4 | 5 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =18A | | 85 | 99 | mΩ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =50V,V _{GS} =0V, F=1.0MHz | | 2800 | 3200 | pF |
| Output Capacitance | C _{oss} | | | 96 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | 6 | | pF |
| Total Gate Charge | Q _g | V _{DS} =480V,I _D =18A, V _{GS} =10V | | 55 | 60 | nC |
| Gate-Source Charge | Q _{gs} | | | 16.5 | | nC |
| Gate-Drain Charge | Q _{gd} | | | 25.5 | | nC |
| Gate plateau voltage | V _{gp} | | | 7.3 | | V |
| Intrinsic gate resistance | R _G | f = 1 MHz open drain | | 1.5 | | Ω |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =380V,I _D =18A, R _G =1.7Ω,V _{GS} =10V | | 15 | | nS |
| Turn-on Rise Time | t _r | | | 14 | | nS |
| Turn-Off Delay Time | t _{d(off)} | | | 72 | | nS |
| Turn-Off Fall Time | t _f | | | 14 | | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I _{SD} | T _C =25℃ | | | 36 | A |
| Pulsed Source-drain current(Body Diode) | I _{SDM} | | | | 108 | A |
| Forward On Voltage | V _{SD} | T _J =25℃,I _{SD} =36A,V _{GS} =0V | | 1.0 | 1.2 | V |
| Reverse Recovery Time | t _{rr} | T _J =25℃,I _F =18A,di/dt=100A/μs | | 160 | | nS |
| Reverse Recovery Charge | Q _{rr} | | | 0.96 | | uC |
| Peak Reverse Recovery Current | I _{rrm} | | | 12 | | A |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

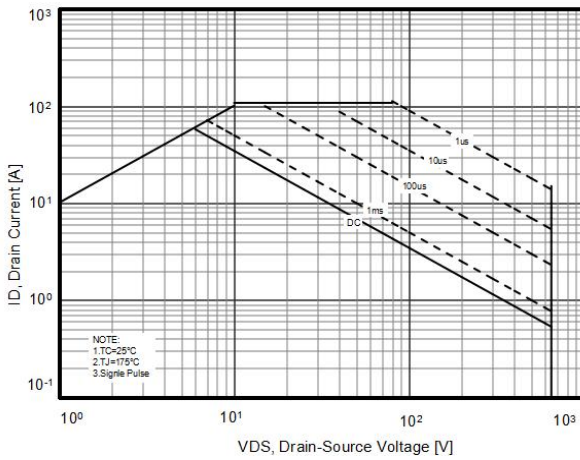


Figure2. Capacitance

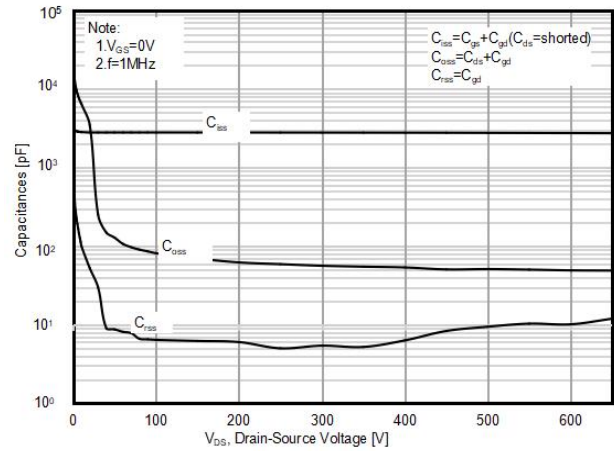


Figure3. Output characteristics

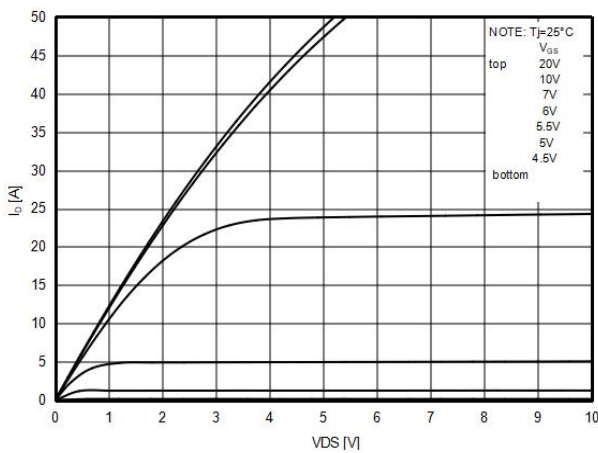


Figure4. Source-Drain Diode Forward Voltage

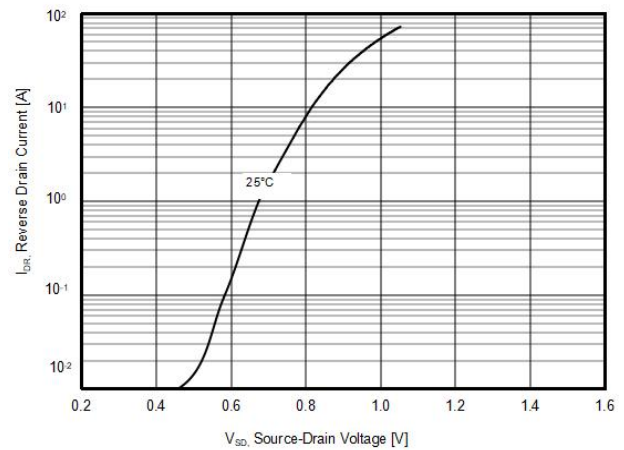


Figure5. Static drain-source on resistance

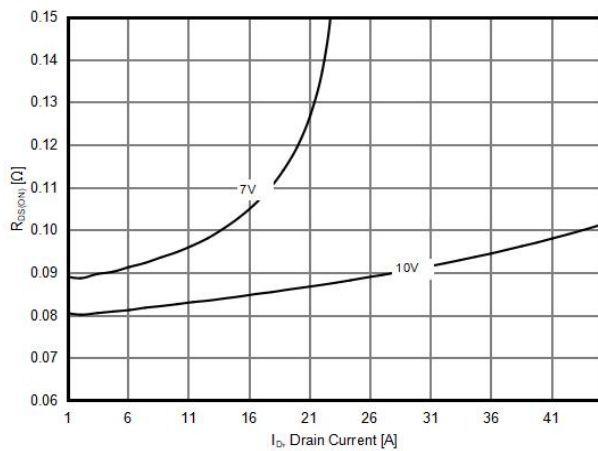


Figure6. Transfer characteristics

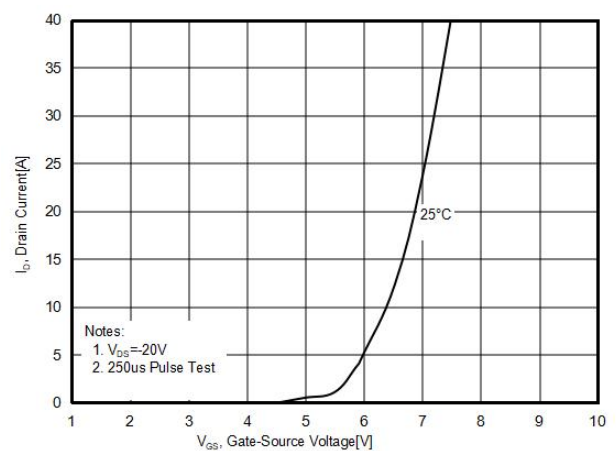


Figure7. $R_{DS(ON)}$ vs Junction Temperature

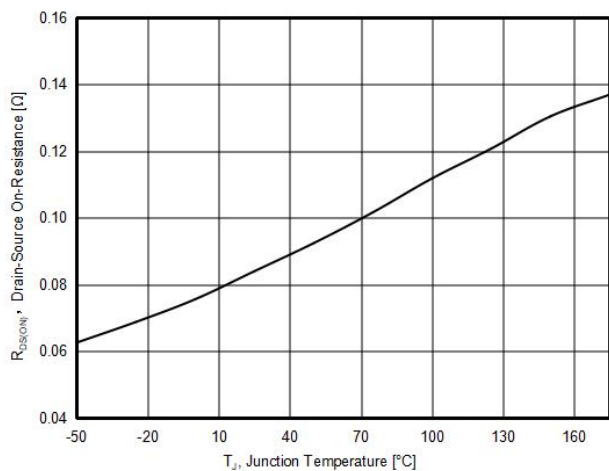


Figure8. BV_{DSS} vs Junction Temperature

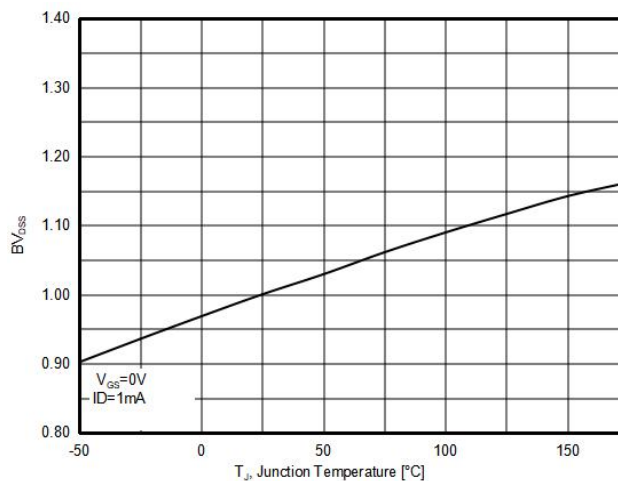


Figure9. Gate charge waveforms

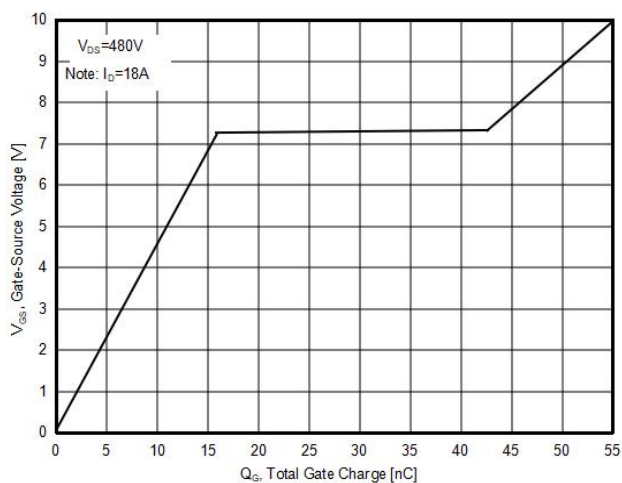
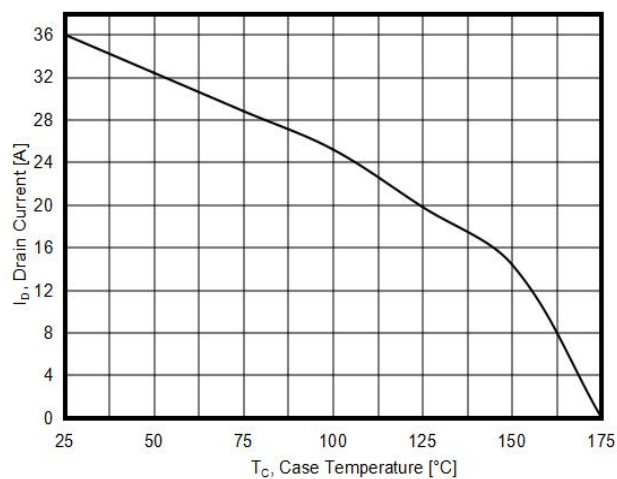
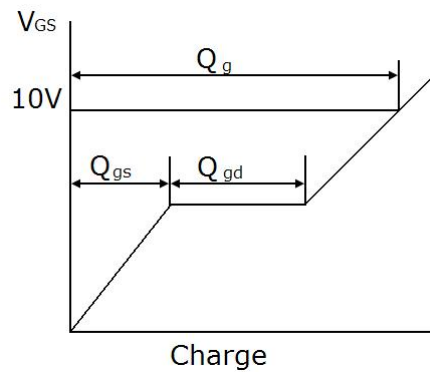


Figure10. Maximum I_D vs Junction Temperature

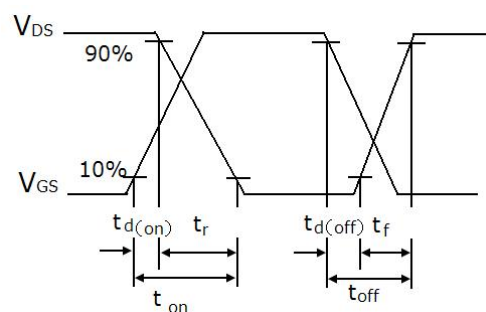
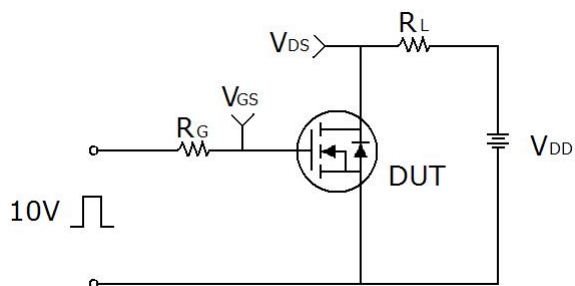


Test circuit

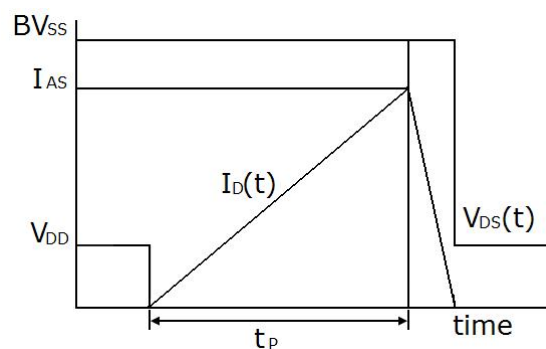
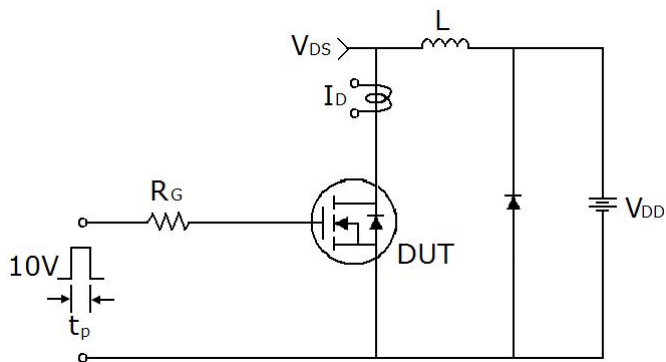
1) Gate charge test circuit & Waveform



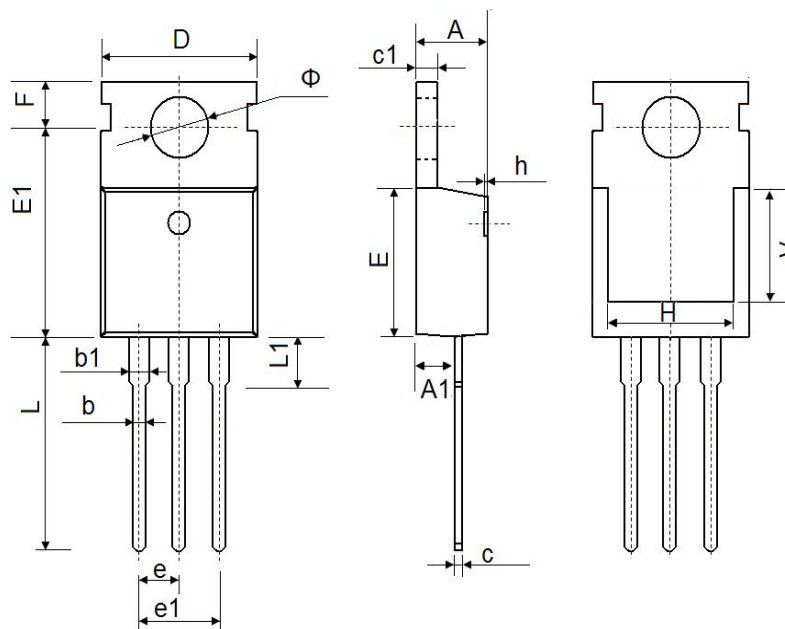
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms



TO-220-E Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.20 | 4.60 | 0.165 | 0.181 |
| A1 | 2.25 | 2.55 | 0.089 | 0.100 |
| b | 0.70 | 0.90 | 0.028 | 0.035 |
| b1 | 1.17 | 1.37 | 0.046 | 0.054 |
| c | 0.33 | 0.65 | 0.013 | 0.026 |
| c1 | 1.20 | 1.40 | 0.047 | 0.055 |
| D | 9.91 | 10.25 | 0.390 | 0.404 |
| E | 8.95 | 9.75 | 0.352 | 0.384 |
| E1 | 12.80 | 12.90 | 0.504 | 0.508 |
| e | 2.54BSC | | 0.100BSC | |
| e1 | 5.08BSC | | 0.200BSC | |
| F | 2.65 | 2.95 | 0.104 | 0.116 |
| H | 7.90 | 8.10 | 0.311 | 0.319 |
| L | 12.90 | 13.40 | 0.508 | 0.528 |
| L1 | 2.85 | 3.25 | 0.112 | 0.128 |
| Φ | 3.40 | 3.80 | 0.134 | 0.150 |

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